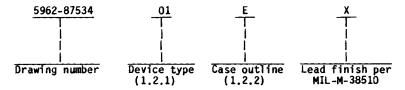
REVISIONS **APPROVED** DATE DESCRIPTION LTR Corrections to figure 1. **28 MAY** 1987 Pages 10 and 11; correct t_{pd} symbols 19 OCT 1987 Change drawing CAGE code to 67268. Editorial changes throughout. REV PAGE В В В В **REV** В **REV STATUS** 10 5 8 **OF PAGES** PAGES 1 MILITARY DRAWING PREPARED, BY **Defense Electronics** This drawing is available for use by **Supply Center** all Departments and Agencies of the Dayton, Ohio CHECKED Department of Defense TITLE: MICROCIRCUITS, DIGITAL, BIPOLAR, QUAD BUS TRANSCEIVER, MONOLITHIC SILICON Original date of drawing: 31 March 1987 CODE IDENT. NO. DWG NO. 5962-87534 SIZE 67268 Α OF REV PAGE 12 AMSC N/A 5962-E595

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

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- 1. SCOPE
- 1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of $\overline{\text{MIL}}$ -STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device types shall identify the circuit function as follows:

Device type	Generic number	Circuit function				
01	26S12	Quad bus transceiver				
02	26S12A	Quad bus transceiver				

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
E F 2	D-2 (16-lead, 1/4" x 7/8") dual-in-line package F-5 (16-lead, 1/4" x 3/8") flat package C-2 (20-terminal, .350" x .350") square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range	-0.5 V to +7.0 V
Input voltage range	-1.5 V to +7.0 V
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P_D) $\frac{1}{2}$	0.7 M
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ_{JC}) :	
Case E	25°C/W
Case F	20°C/W
Case 2	20°C/W
Junction temperature (T_J)	+150°C
DC input current	
DC output current into output receiver	+30 mA
DC output current into bus	200 mA

1/ Must withstand the added PD due to short circuit test (e.g., I_{OS}).

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1.4 Recommended operating conditions.

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Supply voltage (V_{CC}) - - - - - - - - - - - - +4.5 V to +5.5 V Ambient operating temperature range (T_A) - - - - - - - 55°C to +125°C Driver characteristics:

Min high level input voltage (V_{IH}) - - - - - - 2.0 V Max low level input voltage (V_{IL}) - - - - - - 0.8 V Receiver characteristics:

Device type 01

Min high level input voltage (V_{IH}) - - - - - 1.8 V Max low level input voltage (V_{IL}) - - - - - - 1.6 V Device type 02

Min high level input voltage (V_{IH}) - - - - - - 2.05 V Max low level input voltage (V_{IL}) - - - - - - - 1.4 V
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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STU-883

- Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- $3.2\,$ Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
- 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.2.2 Truth table. The truth table shall be as specified on figure 2.
- 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
- 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended ambient operating temperature range.

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Test	Symbol 	Conditions $\begin{array}{cccccccccccccccccccccccccccccccccccc$		Group A subgroups	Device type	Lim Min		Unit	
Power supply current	I _{CC}	V _{CC} = +5.5 V		1, 2, 3) A11 	[70	mA	
Bus leakage current	I I _{BUS}	V _{CC} = +5.5 V or 0 V		1, 2, 3	All	 	100	μА	
DRIVER CHARACTERISTICS	·								-
Low level output voltage	V _{OL}	Y _{CC} = +4.	5 V I _O	0L = 60 mA (N = 2.0 V	1, 2, 3	All	 	0.7	٧
	 	<u>1</u> /	- I ₍ V ₁)L = 100 mA [N = 2.2 V	-{ 	 	 	0.85	٧
Minimum high level input voltage	VIH	<u>2/</u>			1, 2, 3	A11	2.0	 	٧
Minimum low level input voltage	AIL	2/			1, 2, 3	A11		0.8	٧
Input clamp voltage	VIC	 V _{CC} = +4.5 V I _{IN} = -18 mA		1, 2, 3	A11 		 -1.2 	٧	
High level input current	I I I I I	V _{CC} = +5. V _{IN} = 5.5	5 V V		1, 2, 3	 A11 	 	1.0	mA
	I I _{IH2}	V _{CC} = 5.5 V _{IN} = 2.4	V V		1, 2, 3	All		 40 	μА
Low level input current	IIL	V _{CC} = 5.5 V _{IN} = 0.4	V V	•	1, 2, 3	A11	 	 -1.6 	mA
see footnotes at end of ta	ble.								
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Test	Symbol	Conditi -55°C < TA < 4.5 V < V _C U unless otherwi	Group A subgroups	Device type	Limi Min 		Unit	
ECEIVER CHARACTERISTICS								
High level output voltage	V _{OH}	V _{CC} = +4.5 V V _{IN} = V _{IL} I _{OH} = -800 µA (receiver)		1, 2, 3	A11	2.4		٧
Low level output voltage	V _{OL} 		1, 2, 3	A11		0.5	V	
Minimum high level input	ν _{IH}	 E = 0.0 V		1, 2, 3	01	1.8	2.2	٧
voltage 	 	Ii = 0.0 V			02	2.05	2.45	٧
Maximum low level input voltage	VIL				01	1.2	1.6	٧
	<u> </u> 	<u> </u> -		-	02	1.0	1.4	V
Input threshold margin	Î V _{TM} Î			<u> </u>	All	0.4		V
Output short circuit current	I I _{OS}	V _{CC} = 5.5 V V _{OUT} = 0.0 V	<u>3</u> /	1, 2, 3	 A11 	 -20 	-55 	mA
Turn off delay input	t _{PLH1}		4/	9	A11] [111	l I ns
to bus	 	See figure 4	<u>5</u> /	9, 10, 11	i 	i I I	20 	l ns
Turn on delay input	t _{PHL1}	R _L = 500Ω C _L = 300 pF	4/	9	A11		21	ns
to bus	<u> </u>	See figure 4	<u>5</u> /	9, 10, 11	 	 	32	ns
See footnotes at end of ta	ble.		<u> </u>	<u> </u>		•	<u>, , , , , , , , , , , , , , , , , , , </u>	<u> </u>
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Test	Symbol 	Condit -55°C < Ta 4.5 V < VO unless otherw	ions $ \frac{4}{C} + 125$ °C $ \frac{4}{C} \le 5.5$ V ise specified	Group A subgroups	Device type	Limi Min		Unit	
Turn off delay enable	t _{PLH2}	$R_L = 50\Omega$	4/	9	01		17	ns	
to bus		CL = 15 pF See figure 4		ļ	02		15	ns	
			<u>5</u> /	9, 10, 11	01		28	ns	
					02		25	ns	
Turn on delay enable to bus	tpHL2	R _L = 500	C _i = 15 pF	4/	9	A11		15	ns
				<u>5</u> /	9, 10, 11	 		25	ns
Turn off delay bus to output	tpLH3	 C _L = 15 pF See figure 4	4/	9	A11		26	ns	
	 	 	<u>5</u> /	9, 10, 11	 		30	ns	
Turn on delay bus to output	tpHL3	 C _L = 15 pF See figure 4	4/	9	A11		26	ns	
	}		5/	9, 10, 11	 		30	ns	

^{1/} For case F, the output current must be limited to 60 mA or the maximum ambient temperature limited to +125 C for correct operation.

parameters.
Not more than one output should be shorted at a time and the duration of the short circuit test should not exceed 1 second. VCC = 5.0 V dc. VCC = 4.5 V to 5.5 V dc.

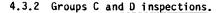
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Input thresholds are tested during dc tests and may be done in combination with testing of other dc

- $3.4\,$ Marking. Marking shall be in accordance with MIL-STD-883 (see $3.1\,$ herein). The part shall be marked with the part number listed in $1.2\,$ herein. In addition, the manufacturer's part number may also be marked as listed in $6.4\,$ herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroups 7 and 8 tests shall verify the truth table.

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- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

^{*} PDA applies to subgroup 1.

5. PACKAGING

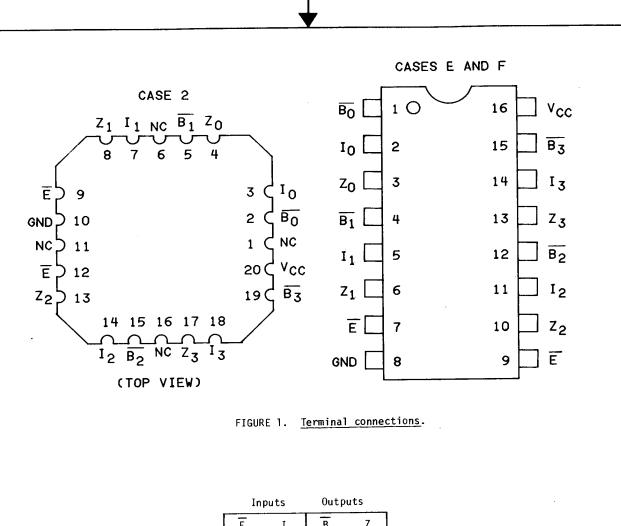
5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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^{**}Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

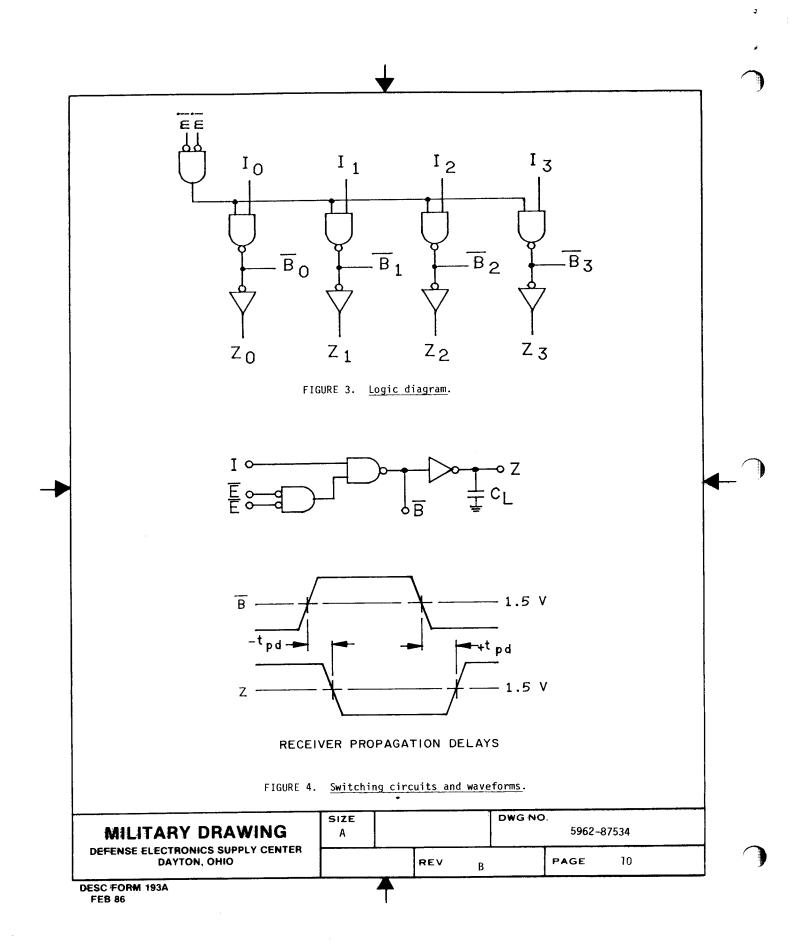


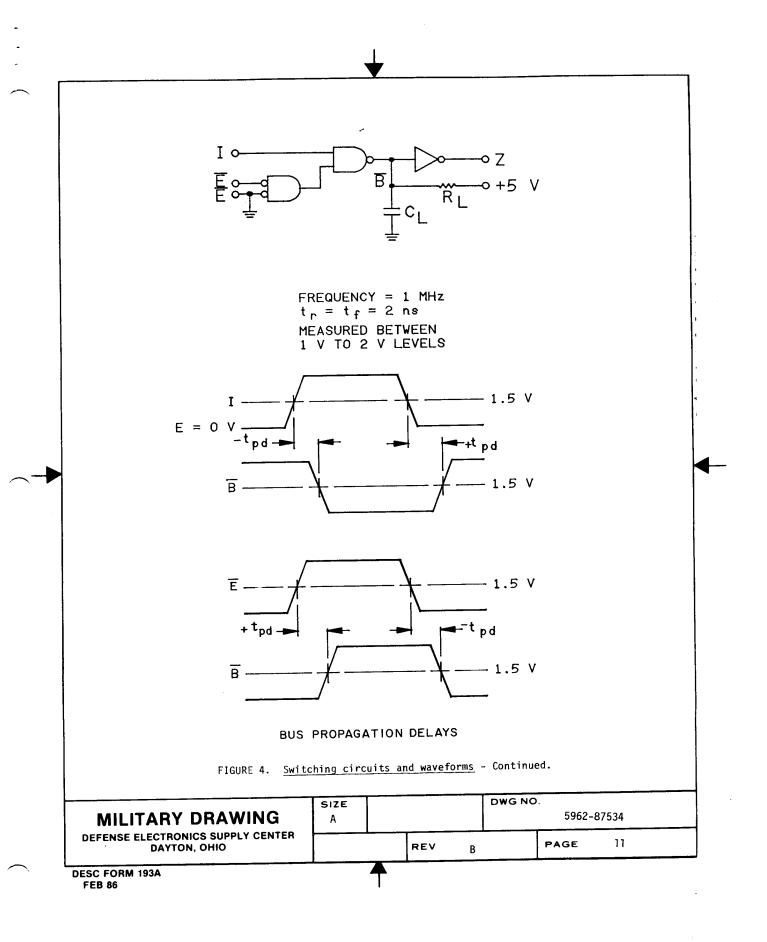
In	puts	Outp	uts
Ē	I	В	Z
L	L	Н	L
L	н	L	Н
Н	Х	Y	Y

H = HIGH voltage level
L = LOW voltage level
X = Don't care
Y = Voltage level of bus

FIGURE 2. Truth table.

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6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /		
5962-8753401EX	34335	AM26S12/BEA		
5962-8753401FX	34335	 AM26S12/BFA 		
5962-87534012X	34335	 AM26S12/B2C 		
5962-8753402EX	34335	AM26S12A/BEA		
5962-8753 4 02FX	34335	 AM26S12A/BFA 		
5962-8753 4 022X	34335	 AM26S12A/B2C 		

 $\frac{1}{I \text{ Laution.}}$ Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34335

Vendor name and address

Advanced Micro Devices, Incorporated 901 Thompson Place P.O. Box 3453 Sunnyvale, CA 94088

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